

MODEL: HSS21-B20-P53 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 or TO-218 package
- solder pin
- aluminum alloy



MODEL

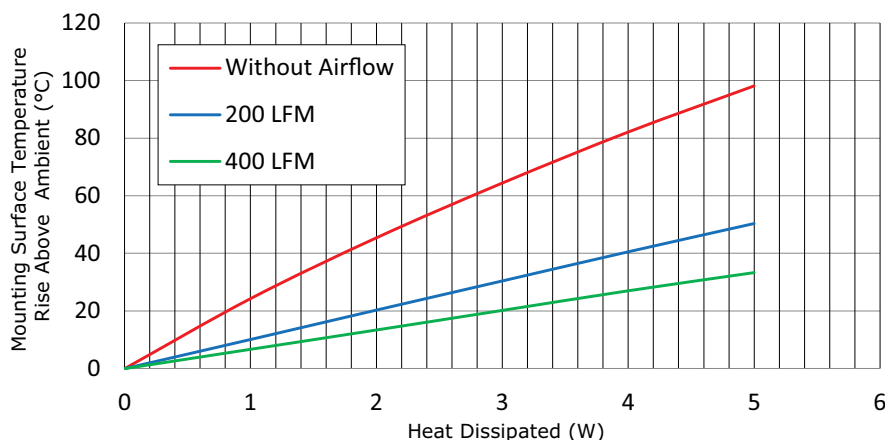
HSS21-B20-P53	thermal resistance ¹			power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	20.93	24.3	10.1	3.58

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	24.3	10.1	6.7
2	45.4	20.3	13.4
3	64.4	30.4	20.2
4	82.1	40.5	27.0
5	98.1	50.3	33.3

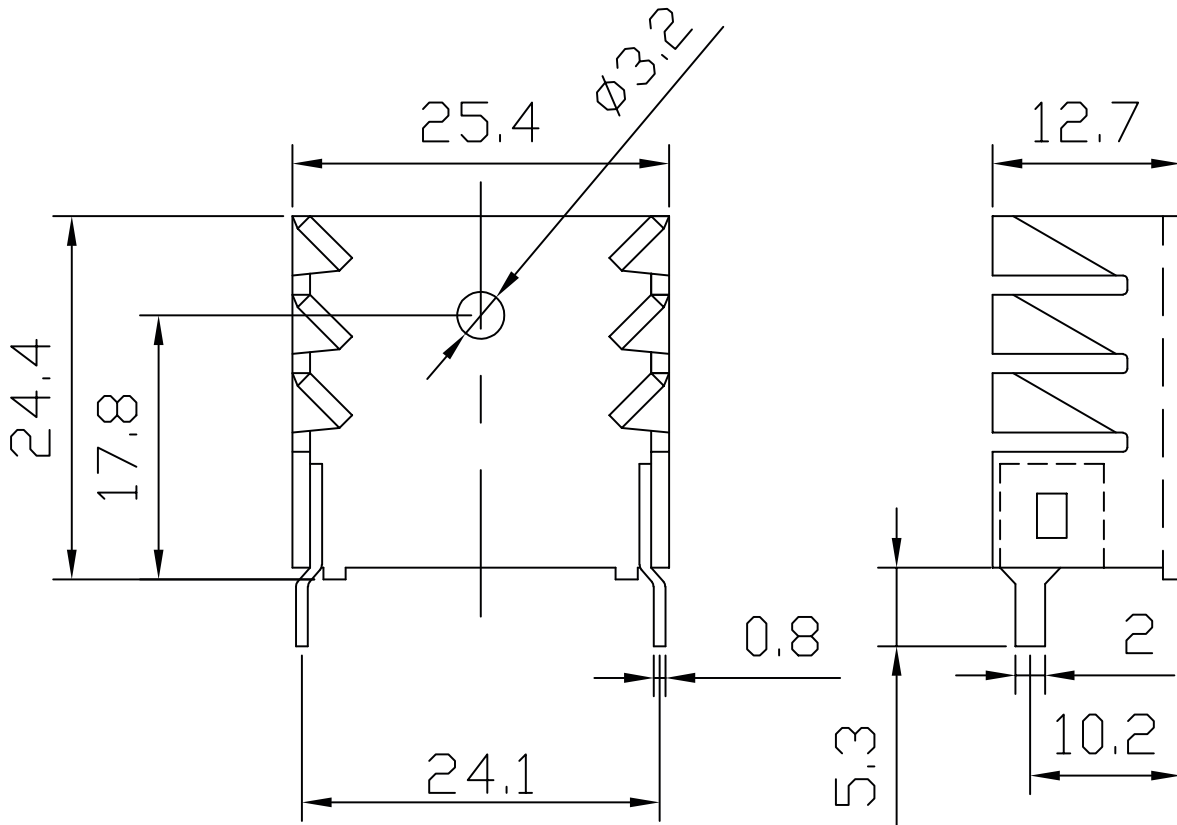
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	4.6 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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